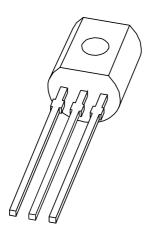
## DISCRETE SEMICONDUCTORS

# DATA SHEET



## MPSA44 NPN high-voltage transistor

Product data sheet Supersedes data of 1999 Apr 27 2004 Oct 11



NXP Semiconductors Product data sheet

## NPN high-voltage transistor

MPSA44

#### **FEATURES**

- Low current (max. 300 mA)
- High voltage (max. 400 V).

#### **APPLICATIONS**

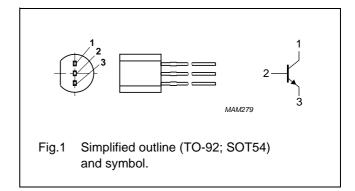
• Telecommunication applications.

#### **DESCRIPTION**

NPN high-voltage transistor in a TO-92; SOT54 plastic package.

#### **PINNING**

PIN	DESCRIPTION
1	collector
2	base
3	emitter



#### **ORDERING INFORMATION**

TYPE NUMBER			
ITPE NUMBER	NAME	DESCRIPTION	VERSION
MPSA44	SC-43A	plastic single-ended leaded (through hole) package; 3 leads	SOT54

### **LIMITING VALUES**

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V <sub>CBO</sub>	collector-base voltage	open emitter	_	500	V
V <sub>CEO</sub>	collector-emitter voltage	open base	-	400	V
V <sub>EBO</sub>	emitter-base voltage	open collector	_	6	V
I <sub>C</sub>	collector current (DC)		_	300	mA
I <sub>CM</sub>	peak collector current		_	600	mA
I <sub>BM</sub>	peak base current		_	100	mA
P <sub>tot</sub>	total power dissipation	T <sub>amb</sub> ≤ 25 °C; note 1	-	625	mW
T <sub>stg</sub>	storage temperature		-65	+150	°C
Tj	junction temperature		_	150	°C
T <sub>amb</sub>	ambient temperature		-65	+150	°C

#### Note

1. Transistor mounted on an FR4 printed-circuit board.

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#### THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R <sub>th(j-a)</sub>	thermal resistance from junction to ambient	note 1	200	K/W

#### Note

1. Transistor mounted on an FR4 printed-circuit board.

#### **CHARACTERISTICS**

 $T_{amb}$  = 25 °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
I <sub>CBO</sub>	collector-base cut-off current	V <sub>CB</sub> = 400 V; I <sub>E</sub> = 0 A	Ī-	100	nA
		$V_{CB} = 400 \text{ V}; I_E = 0 \text{ A}; T_j = 150 ^{\circ}\text{C}$	-	10	μΑ
I <sub>EBO</sub>	emitter-base cut-off current	V <sub>EB</sub> = 4 V; I <sub>C</sub> = 0 A	-	100	nA
h <sub>FE</sub>	DC current gain	V <sub>CE</sub> = 10 V; I <sub>C</sub> = 1 mA	40	_	
		$V_{CE} = 10 \text{ V}; I_{C} = 10 \text{ mA}$	50	200	
		V <sub>CE</sub> = 10 V; I <sub>C</sub> = 50 mA; note 1	45	_	
		V <sub>CE</sub> = 10 V; I <sub>C</sub> = 100 mA; note 1	40	_	
V <sub>CEsat</sub>	collector-emitter saturation voltage	I <sub>C</sub> = 1 mA; I <sub>B</sub> = 0.1 mA	-	400	mV
		$I_C = 10 \text{ mA}; I_B = 1 \text{ mA}$	_	500	mV
		$I_C = 50 \text{ mA}$ ; $I_B = 5 \text{ mA}$ ; note 1	_	750	mV
V <sub>BEsat</sub>	base-emitter saturation voltage	I <sub>C</sub> = 10 mA; I <sub>B</sub> = 1 mA; note 1	-	850	mV
C <sub>c</sub>	collector capacitance	$V_{CB} = 20 \text{ V}; I_E = i_e = 0 \text{ A}; f = 1 \text{ MHz}$	-	7	pF
C <sub>e</sub>	emitter capacitance	$V_{EB} = 0.5 \text{ V}; I_C = I_C = 0 \text{ A}; f = 1 \text{ MHz}$	_	180	pF
f <sub>T</sub>	transition frequency	$V_{CE} = 10 \text{ V}; I_{C} = 10 \text{ mA}; f = 100 \text{ MHz}$	20	_	MHz

#### Note

1. Pulse test:  $t_p \le 300~\mu s;~\delta \le 0.02.$ 

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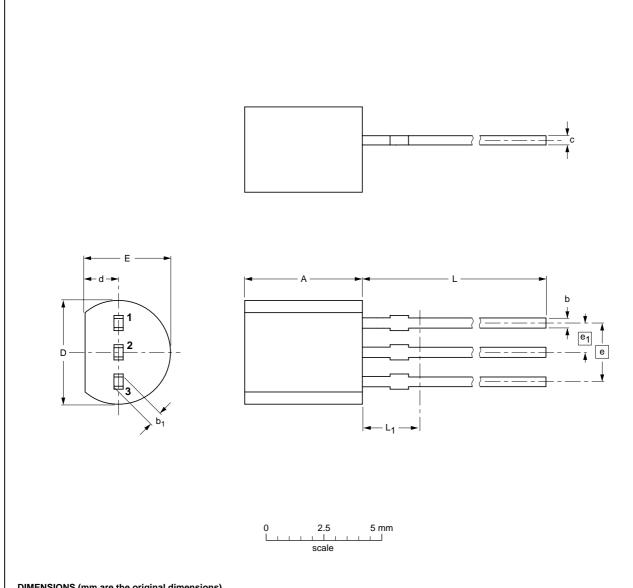
## NPN high-voltage transistor

MPSA44

#### **PACKAGE OUTLINE**

### Plastic single-ended leaded (through hole) package; 3 leads

SOT54



#### DIMENSIONS (mm are the original dimensions)

UNIT	Α	b	b <sub>1</sub>	С	D	d	E	е	e <sub>1</sub>	L	L <sub>1</sub> <sup>(1)</sup> max.	
mm	5.2 5.0	0.48 0.40	0.66 0.55	0.45 0.38	4.8 4.4	1.7 1.4	4.2 3.6	2.54	1.27	14.5 12.7	2.5	

1. Terminal dimensions within this zone are uncontrolled to allow for flow of plastic and terminal irregularities.

OUTLINE		REFER	EUROPEAN	ISSUE DATE		
VERSION	IEC	JEDEC	JEITA		PROJECTION	ISSUE DATE
SOT54		TO-92	SC-43A			<del>-04-06-28</del> 04-11-16

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### NPN high-voltage transistor

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#### **DATA SHEET STATUS**

DOCUMENT STATUS <sup>(1)</sup>	PRODUCT STATUS <sup>(2)</sup>	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

#### **Notes**

- 1. Please consult the most recently issued document before initiating or completing a design.
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#### **Customer notification**

This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content, except for package outline drawings which were updated to the latest version.

#### **Contact information**

For additional information please visit: http://www.nxp.com
For sales offices addresses send e-mail to: salesaddresses@nxp.com

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